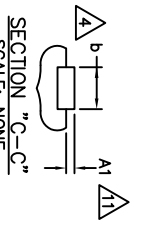
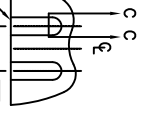
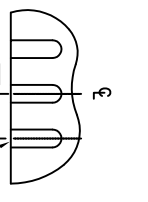
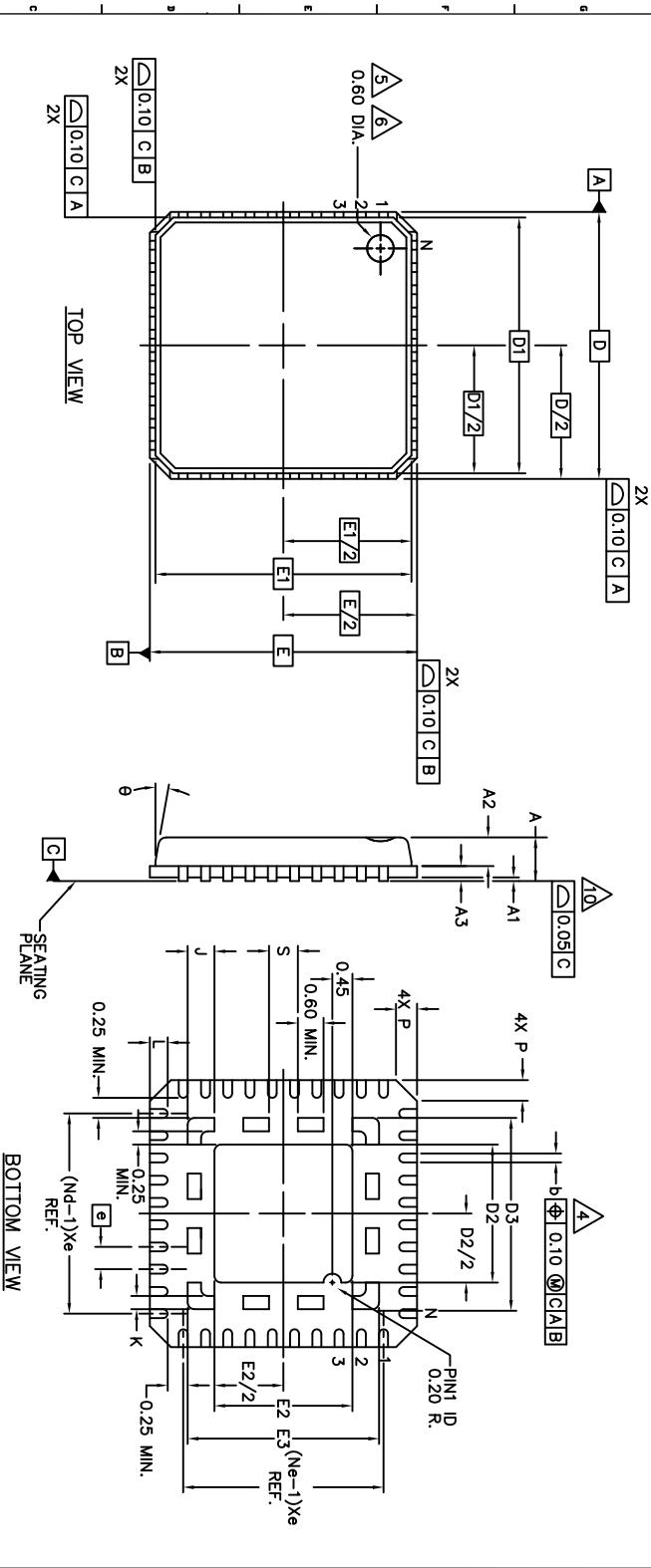


NOTES : ANY MOLD FLASH ON THE RING PAD AREA SHALL BE ALLOWABLE.

MIXED RING HIGH DENSITY LEADFRAME



Author: Schneider, Inc. Designer: Andrew, USA Author: Sankaranarayanan, Inc. Author: Technology/Philippines, Inc. Manila, Philippines	
PACKAGE OUTLINE, MLF-2, 6 X 6 mm BODY	
DATE: 4/27/78	DWG NO: 06
PRINTING IS SCALED TO FIT DO NOT SCALE DRAWING	
3 OF 5	5